

2SB1435

Silicon PNP epitaxial planar type

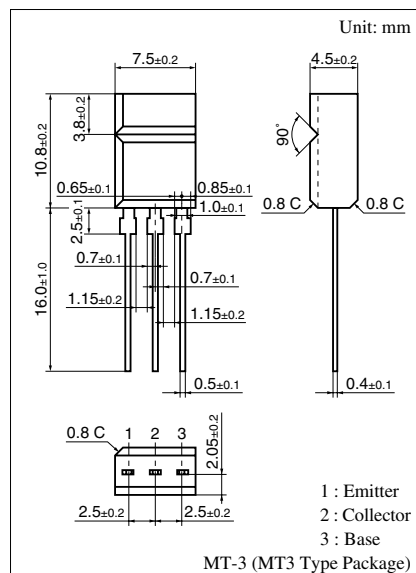
For low-frequency output amplification

■ Features

- Low collector to emitter saturation voltage $V_{CE(sat)}$
- Large collector current I_C
- Allowing automatic insertion with radial taping

■ Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector to base voltage	V_{CBO}	-50	V
Collector to emitter voltage	V_{CEO}	-50	V
Emitter to base voltage	V_{EBO}	-5	V
Peak collector current	I_{CP}	-3	A
Collector current	I_C	-2	A
Collector power dissipation	P_C	1.5	W
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

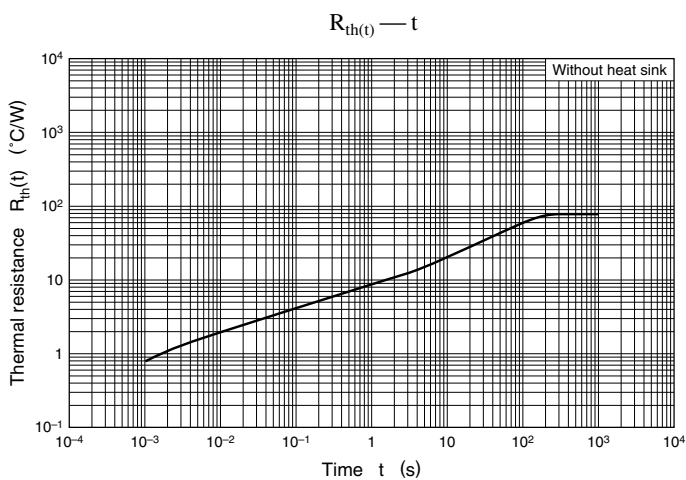
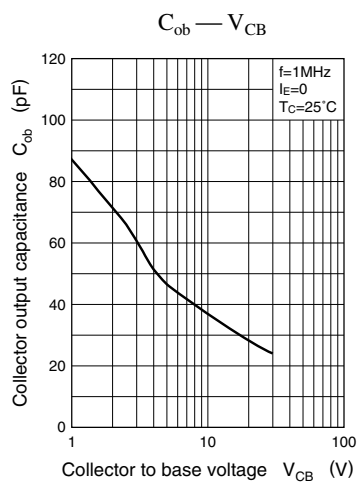
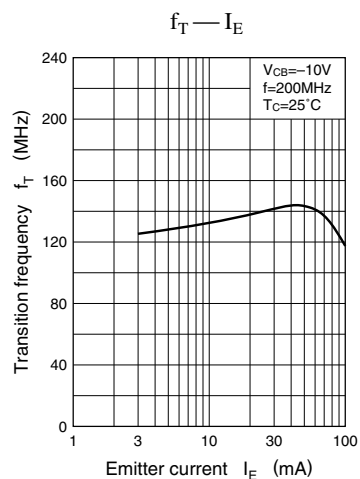
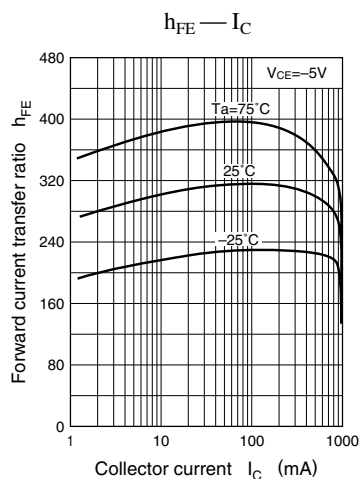
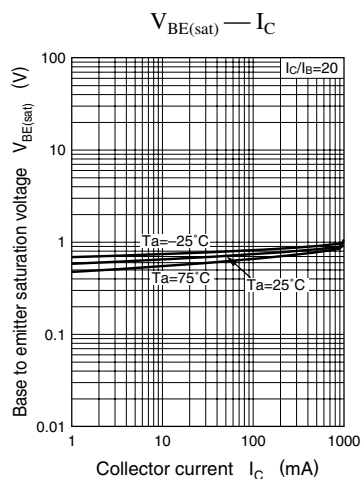
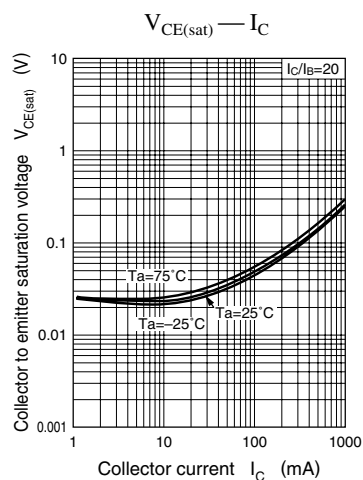
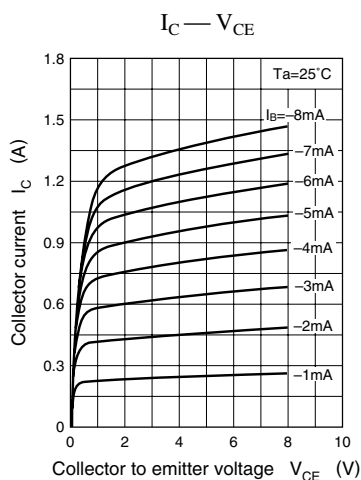
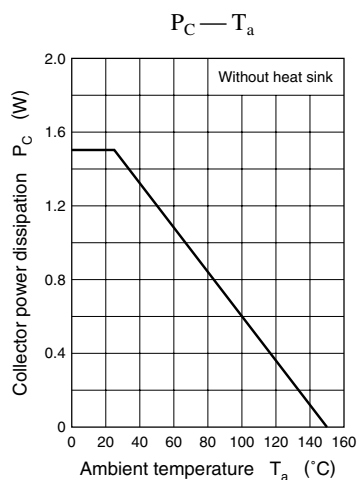


■ Electrical Characteristics $T_C = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector cutoff current	I_{CBO}	$V_{CB} = -20\text{ V}, I_E = 0$			-0.1	μA
Collector to base voltage	V_{CBO}	$I_C = -10\text{ }\mu\text{A}, I_E = 0$	-50			V
Collector to emitter voltage	V_{CEO}	$I_C = -1\text{ mA}, I_B = 0$	-50			V
Emitter to base voltage	V_{EBO}	$I_E = -10\text{ }\mu\text{A}, I_C = 0$	-5			V
Forward current transfer ratio	h_{FE1}^*	$V_{CE} = -2\text{ V}, I_C = -200\text{ mA}$	120		340	
	h_{FE2}	$V_{CE} = -2\text{ V}, I_C = -1\text{ A}$	60			
Collector to emitter saturation voltage	$V_{CE(sat)}$	$I_C = -1\text{ A}, I_B = -50\text{ mA}$		-0.2	-0.3	V
Base to emitter saturation voltage	$V_{BE(sat)}$	$I_C = -1\text{ A}, I_B = -50\text{ mA}$		-0.85	-1.2	V
Transition frequency	f_T	$V_{CB} = -10\text{ V}, I_E = 50\text{ mA}, f = 200\text{ MHz}$		80		MHz
Collector output capacitance	C_{ob}	$V_{CB} = -10\text{ V}, I_E = 0, f = 1\text{ MHz}$		45	60	pF

Note) *: Rank classification

Rank	R	S
h_{FE1}	120 to 240	170 to 340



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